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Ameritech's Electronic Bonding Gateway Interface

References material to CPE vendors for Ameritech's Electronic Bonding Interface Specifications

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1. INTRODUCTION

1.1. *General*

This document describes a new Electronic Bonding Gateway interface that will provide an application to application interface to Ameritech for Trouble Administration. It converts gateway messages to Loop Maintenance Operations System (LMOS) and Work Force Administration System (WFA) transmissions required to initiate, manage, and close maintenance trouble reports.

The Electronic Bonding Gateway is defined as an X.25G Packet Switched Port connection to an Open systems Interconnection (OSI) seven layer application stack. This stack allows for transmission of application-to-application protocol specific messages and provides peer authentication. The gateway will use Common Management Information Protocol (CMIP) protocol.

The initial business function provided by the Ameritech Electronic Bonding Gateway is:

Trouble Administration - A remote mechanism for Special Access, Switched Access, and exchange services customers to manage their trouble reports.

1.2. *Reasons for Reissue*

If Ameritech should decide to implement any future Electronic Bonding Gateway enhancements, this document will be reissued and the reason for the reissue will be outlined in this section.

2. AMERITECH'S ELECTRONIC BONDING GATEWAY

2.1. *Purpose*

Ameritech's Electronic Bonding Gateway Interface is the point of connection between Electronic Bonding compatible Customer Premises Equipment and the Ameritech Electronic Bonding Gateway. It allows a customer to create and manage Trouble Reports submitted to Ameritech on a computer application to application basis.

2.2. *Capabilities*

The Electronic Bonding Gateway Interface is described in the three ANSI Standards discussed below.

In addition to the Telecommunications Trouble Report, the T1.227 standard describes several optional objects that provide additional capabilities. Table 1 lists the managed objects in the standard and shows which ones Ameritech will implement as part of this offering. Others will be considered for implementation as customer system needs evolve.

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Table 1.

Object	
Account	x
Customer Network Management Service	x
Contact	
Telecommunications Trouble Report	x
Repair Activity	
Service Profile	
Trouble History Record	
Trouble Report	x
Trouble Report Format Definition	x

The T1.228 standard describes a number of functional units that provide additional functions to the basic trouble report process. Table 2 lists the functional units and shows which ones Ameritech will implement as part of this offering.

Table 2.

Functional Units	
Kernel - Create a Telecommunications Trouble Report	x
Kernel - Get information from a Telecommunications Trouble Report	x
Request Trouble Report Format	
Trouble History Event Notificaoon	
Review Trouble History Record	
Add Trouble Information	x
Trouble Report Status / Commitment Time Update Notification	
Verify Trouble Report Completion	x
Modify Trouble Administration Information	x
Trouble Administration Configuration Event Notification	x
Trouble Report Progress Notificaton	
Cancel Trouble Report	x

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The T1.224 Standard describes a 7-layer Open Systems Interconnection protocol stack to be used to interconnect the Customer Provided Equipment with the Ameritech Electronic Bonding Gateway.

3. REFERENCES

1. T1.227-1992 - American National Standard for Telecommunications - Operation, Administration, Maintenance and Provisioning (OAM&P) - Extension to Generic Network Model for Interfaces between Operations Systems across Jurisdictional Boundaries to Support Fault Management (Trouble Administration).
2. T1.228-1992 - American National Standard for Telecommunications - Operations, Administration, Maintenance and Provisioning (OAM&P) - Services for Interfaces between Operations Systems across Jurisdictional Boundaries to Support Fault Management (Trouble Administration).
3. T1.225-1992 - American National Standard for Telecommunications - Operation, Administration, Maintenance and Provisioning (OAM&P) - Protocols for Interfaces between Operations Systems in Different Jurisdictions.

NOTE: References 1 through 3 may be ordered from:

American National Standards Institute, 11 West 42nd Street, New York, New York, 10036

Any questions regarding this document, please contact the APEx Help Desk at 847-248-4328.